
Introduction to Electromagnetic Compatibility

Second Edition

CLAYTON R. PAUL

*Department of Electrical and Computer Engineering, School of Engineering,
Mercer University, Macon, Georgia and Emeritus Professor of Electrical
Engineering, University of Kentucky, Lexington, Kentucky*



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*This textbook is dedicated to
The humane and compassionate treatment of animals*

*“For every difficult problem there is always a simple answer and most of them
are wrong.”*

“When you can measure what you are speaking about and express it in numbers you know something about it; but when you cannot measure it, when you cannot express it in numbers your knowledge is of meagre and unsatisfactory kind; it may be the beginning of knowledge but you have scarcely progressed in your thoughts to the stage of science whatever the matter may be.”

Lord Kelvin

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